

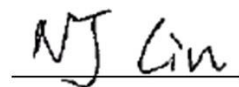
**RoHS Declaration of Conformity****Part Numbers:**XXXXXXXXXXXXXX

Advantech pursues its social responsibility for global environmental preservation, hereby declaring that the product(s) listed above is (are) in conformity with RoHS Directive (2011/65/EU and (EU) 2015/863) of the European Parliament on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

EU RoHS regulated Substances	Threshold *
Cadmium ( Cd ) / Cadmium Compounds	<100 ppm
Lead ( Pb ) / Lead Compounds	<1000 ppm
Mercury(Hg)/Mercury compounds	<1000 ppm
Hexavalent-Chromium (Cr <sup>6+</sup> ) Compounds	<1000 ppm
Polybrominated biphenyls(PBBs)	<1000 ppm
Polybrominated diphenyl ethers(PBDEs)	<1000 ppm
Bis (2-ethylhexyl) phthalate(DEHP)	<1000 ppm
Butyl benzyl phthalate (BBP)	<1000 ppm
Dibutyl phthalate(DBP)	<1000 ppm
Diisobutyl phthalate (DIBP)	<1000 ppm

\*Threshold does not apply to applications covered by a RoHS substance exemption.

- The described product has been assessed and determined compliant with the relevant harmonized standard EN 50581.
- RoHS compliant for some applications using exemption identified below
  - 6(a). Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight.
  - 6(b). Lead as an alloying element in aluminium containing up to 0.4% lead by weight.
  - 6(c). Copper alloy containing up to 4% lead by weight.
  - 7(a). Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
  - 7(c)-I. Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.
  - 7(c)-II. Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher.
  - 8(b). Cadmium and its compounds in electrical contacts
  - 15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.



NJ Lin  
 Corporate Quality / Manager  
 Date: 2018/XX/XX